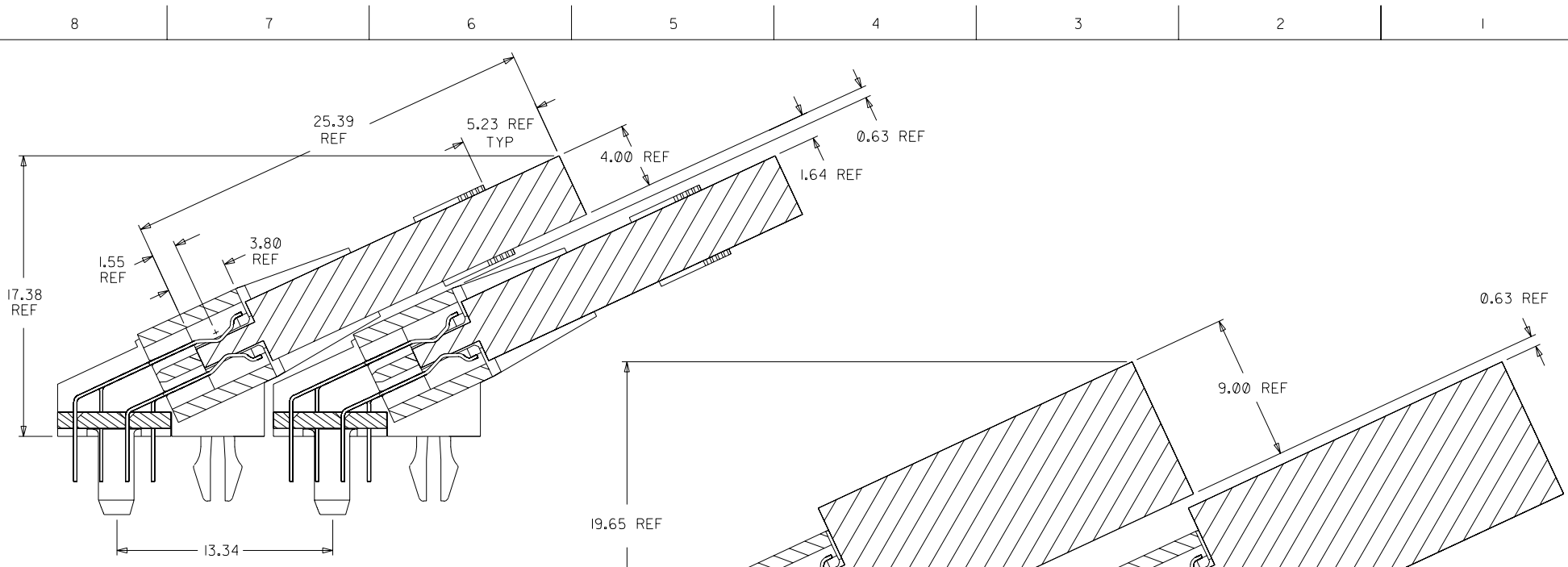


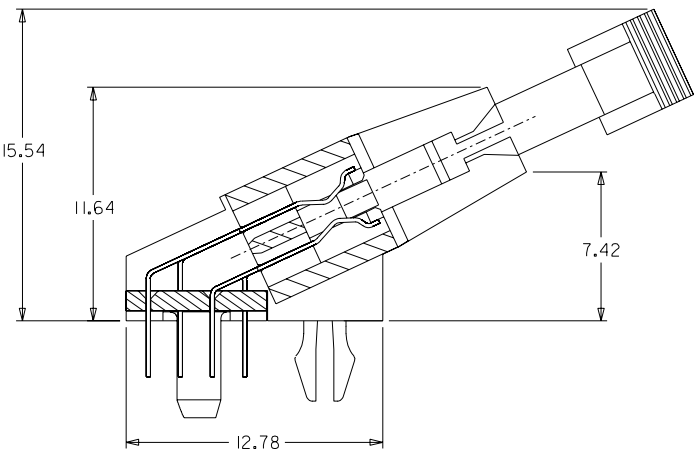
- NOTES:
- MATERIALS: HOUSING, BASEPLATE AND LATCH - HIGH TEMPERATURE THERMOPLASTIC, UL 94-V0  
TERMINAL AND FORKLOCK - COPPER ALLOY
  - FINISHES: CONTACT AREA: SEE TABLE ON SHEET 4  
SOLDER TAILS: 2.54µm/100µ" MIN. TIN/LEAD
  - PRODUCT SPECIFICATIONS: PS-87623-002 FOR PERFORMANCE SPECIFICATIONS.
  - DATE CODE SHALL BE MARKED LEGIBLY AS SHOWN: XX XX  
YEAR WEEK
  - PART NUMBER SHALL BE MARKED LEGIBLY AS SHOWN: 87623-0XXX  
REFER TO TABLE

EC NO. S2003-0507 DRWN:SKHOANG030415 CHK: PT LIM 030513 APPR: SK TOH 030514	QUALITY SYMBOLS MAJOR ▲ = 0 CRITICAL ▽ = 0	GENERAL TOLERANCES: (UNLESS SPECIFIED)		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	DIMENSIONS:		SHT	REV
		4 PLACES	mm	INCH	NTS		<input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	<input type="checkbox"/> mm <input checked="" type="checkbox"/> INCH		
A6	REV	3 PLACES	±0. ---	±.	DRAWN BY & DATE LPLIM 000110	TITILE: 1.27 MM PITCH, 184 CKTS, 25 DEG DDR DIMM	REVISE ON CAD ONLY			
		2 PLACES	±0. ---	±.			CHECKED BY & DATE DSOH 000202	MOLEX MOLEX INCORPORATED		
		1 PLACE	±0. ---	±.	APPROVED BY & DATE TOH 000202	MATERIAL NO. SEE TABLE		DRAWING NO. SD-87623-001	SHEET NO. 1 OF 4	
		ANGULAR: ± 5°		CAD FILENAME SD-87623-001.S01		DRAWING NO. SD-87623-001		SIZE A3		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.										



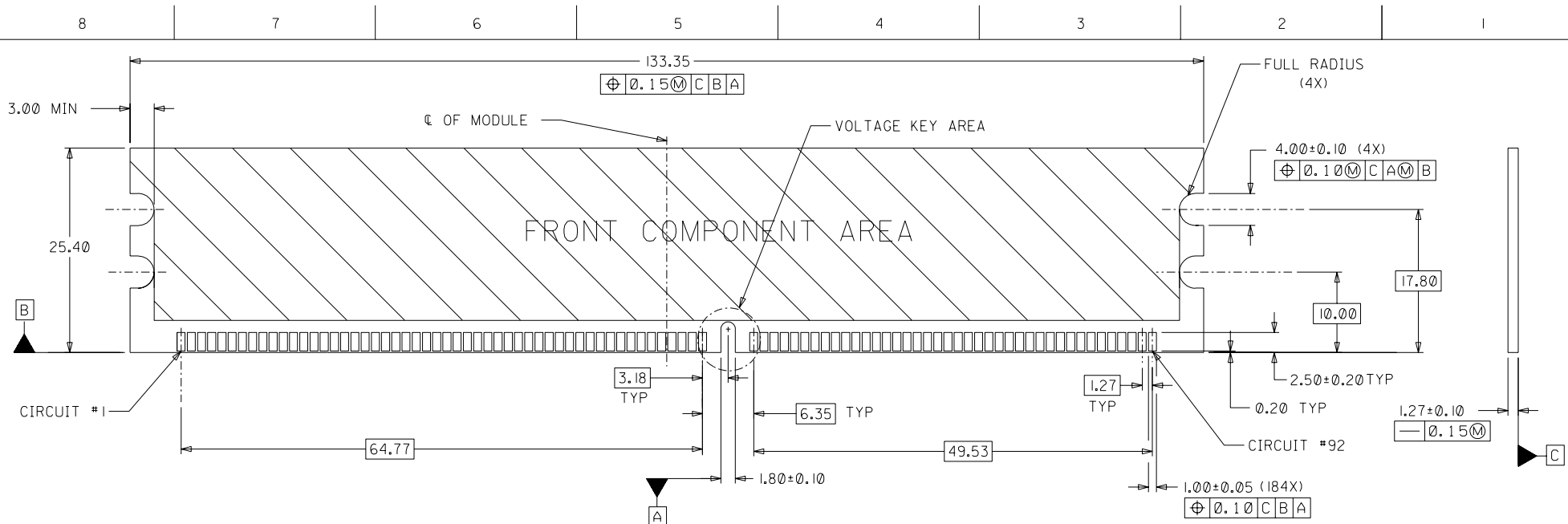
MINIMUM RECOMMENDED ROW TO ROW SPACING  
WHEN USING A 4.00 mm THICK  
MODULE (TYPICAL TSOP PACKAGING)

MINIMUM RECOMMENDED ROW TO ROW SPACING  
WHEN USING A 9.00 mm THICK  
MODULE (TYPICAL SOJ PACKAGING)



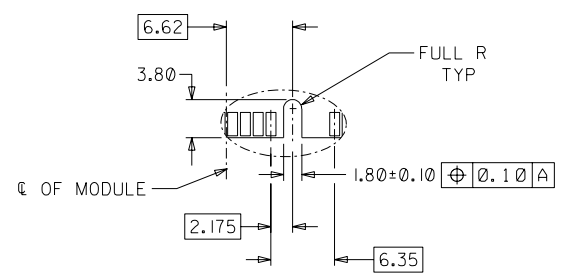
SECTION A-A

EC NO. S2003-0507 DRWN: VSKHOANG030415 CHK: PT LIM 030513 APPR: SK TOH 030514	QUALITY SYMBOLS	GENERAL TOLERANCES: (UNLESS SPECIFIED)		SCALE NTS	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	<input checked="" type="checkbox"/> THIRD ANGLE <input type="checkbox"/> PROJECTION	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY	SHT	REV
	MAJOR ▼ = 0	DESCRIPTION	4 PLACES ±0.--- ±.	3 PLACES ±0.--- ±.	2 PLACES ±0.25 ±.	1 PLACE ±0.--- ±.	ANGULAR: ± 5°	DRAWN BY & DATE LPLIM 000110	
A6	REV	CRITICAL ▽ = 0		CHECKED BY & DATE DSOH 000202		APPROVED BY & DATE TOH 000202		TITLE: 1.27 MM PITCH, 184 CKTS, 25 DEG DDR DIMM	
				CAD FILENAME SD-87623-001.S02		MATERIAL NO. SEE TABLE		DRAWING NO. SD-87623-001	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.								SHEET NO. 2 OF 4	SIZE A3



RECOMMENDED MODULE LAYOUT  
 (PER JEDEC STANDARD MO-206, 184 CKT.)  
 UNLESS OTHERWISE SPECIFIED, GENERAL TOLERANCE FOR MODULE =  $\pm 0.13$

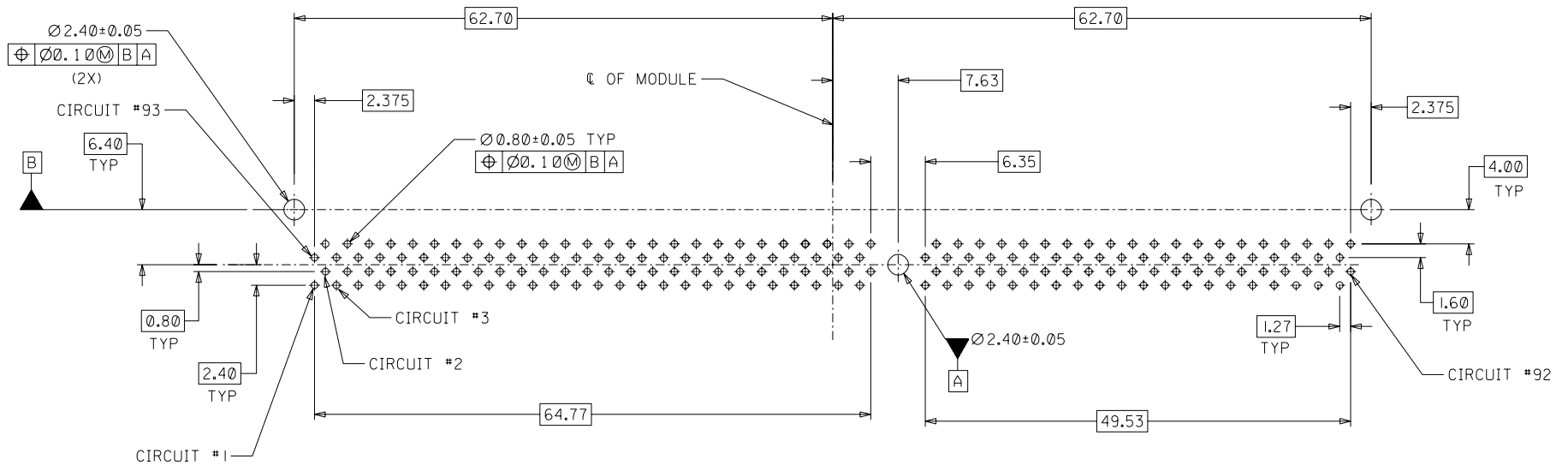
VOLTAGE KEY AREA



OFFSET LEFT KEY  
 (2.5 VOLTS)

EC NO. S2003-0507 DRWN: VSKHOANG030415 CHK: PT LIM 030513 APPR: SK TOH 030514	QUALITY SYMBOLS MAJOR $\blacktriangledown = 0$ CRITICAL $\blacktriangledown = 0$	GENERAL TOLERANCES: (UNLESS SPECIFIED)		SCALE NTS	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	<input checked="" type="checkbox"/> THIRD ANGLE PROJECTION	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input type="checkbox"/> mm <input checked="" type="checkbox"/> mm ONLY	SHT REV
		4 PLACES $\pm 0.---$	mm INCH	DRAWN BY & DATE LPLIM 000110	TITLE: 1.27 MM PITCH, 184 CKTS, 25 DEG DDR DIMM			
		3 PLACES $\pm 0.---$	mm INCH	CHECKED BY & DATE DSOH 000202	<b>MOLEX</b> MOLEX INCORPORATED			
		2 PLACES $\pm 0.25$	mm INCH	APPROVED BY & DATE TOH 000202	CAD FILENAME SD-87623-001.S03	MATERIAL NO. SEE TABLE	DRAWING NO. SD-87623-001	SHEET NO. 3 OF 4
1 PLACE $\pm 0.---$	mm INCH	ANGULAR: $\pm 5^\circ$	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.			SIZE A3		

MATERIAL NO.	VOLTAGE KEY	CKT SIZE	TAIL LENGTH P±0.25	PEG LENGTH Q±0.25	FORK LENGTH R±0.25	RECOMMENDED PCB THICKNESS	FINISHES: CONTACT AREA
87623-0001	LEFT (2.5V)	184	2.79	3.18	3.18	1.57	SELECTIVE GOLD 0.38µM/15µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL
87623-0011			3.18	4.83	3.94		
87623-0012			3.18	3.18	3.18		
87623-0013			3.81	4.83	4.42	2.84	SELECTIVE GOLD 0.76µM/30µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL
87623-0101			2.79	3.18	3.18		
87623-0111			3.18	4.83	3.94		
87623-0113			3.81	4.83	4.42	2.84	



RECOMMENDED  
P.C. BOARD HOLE PATTERN  
(CONNECTOR SIDE)

EC NO. S2003-0507 DRW:VSKHOANG030415 CHK: PT LIM 030513 APPR: SK TOH 030514	QUALITY SYMBOLS	GENERAL TOLERANCES: (UNLESS SPECIFIED)	SCALE NTS	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	THIRD ANGLE PROJECTION	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY	SHT	REV										
	MAJOR ▼ = 0 CRITICAL ▽ = 0	<table border="1"> <tr> <td>4 PLACES</td> <td>±0. ---</td> <td>±.</td> </tr> <tr> <td>3 PLACES</td> <td>±0. ---</td> <td>±.</td> </tr> <tr> <td>2 PLACES</td> <td>±0.25</td> <td>±.</td> </tr> <tr> <td>1 PLACE</td> <td>±0. ---</td> <td>±.</td> </tr> </table> ANGULAR: ± 5°	4 PLACES	±0. ---	±.	3 PLACES	±0. ---	±.	2 PLACES	±0.25	±.	1 PLACE	±0. ---	±.	DRAWN BY & DATE L.P.LIM 000110 CHECKED BY & DATE DSOH 000202 APPROVED BY & DATE TOH 000202	TITLE: 1.27 MM PITCH, 184 CKTS, 25 DEG DDR DIMM		
4 PLACES	±0. ---	±.																
3 PLACES	±0. ---	±.																
2 PLACES	±0.25	±.																
1 PLACE	±0. ---	±.																
A6	REV		CAD FILENAME SD-87623-001.S04	MATERIAL NO. SEE TABLE	DRAWING NO. SD-87623-001	SHEET NO. 4 OF 4												
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.							SIZE A3											